

<b>Notice of References Cited</b>	Application/Control No. 10/748,254	Applicant(s)/Patent Under Reexamination ABE, KAZUHIDE	
	Examiner W. David Coleman	Art Unit 2823	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
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**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

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	W	S. Sankaran, "Development of TiSiN Diffusion Barriers for Cu/SiLK Metallization Schemes" Interconnect Technology Conference, 2000. Proceedings of the IEEE 2000 International, 5-7 June 2000 pp 40-42
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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